

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Previously Presented) A back electrode electronic part comprising:

a main body including a circuit; and

electrodes arranged for solder bumps on a back surface portion of said electronic part and connected to said circuit; wherein

said electrodes are arranged into groups of electrodes at portions of the electrode arrangement;

said groups of electrodes are provided for a single first solder bump which is larger than second solder bumps for said electrodes arranged other than in said groups of electrodes; and

said groups of electrodes includes electrodes having a substantially same potential level when said circuit operates.
2. (Previously Presented) A back electrode electronic part according to claim 1, wherein said electrodes are arranged in a matrix, and said groups of electrodes are corner portions.
3. (Previously Presented) A back electrode electronic part according to claim 1, wherein said group of electrodes includes a non-contact electrode which is not connected to said circuit.

4. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of said electrodes of said group is a signal electrode.

5. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of said electrodes of said group is a ground potential electrode.

6. (Previously Presented) A back electrode electronic part according to claim 1, wherein one of said electrodes of said group is a power supply potential electrode.

7. (Previously Presented) An electronic assembly comprising:
a back electrode electronic part comprising:
a main body including a circuit, and
electrodes arranged on a back surface portion of said electronic part and connected to said circuit, wherein said electrodes are arranged into groups of electrodes at portions of the electrode arrangement;

said groups of electrodes includes said electrodes having a substantially same potential level when said circuit operates;

said electronic assembly further comprising:

a printed circuit board having substrate electrodes corresponding to said electrodes provided for said electronic part, wherein one of said substrate electrodes as a first substrate

electrode is provided for each of said groups of electrodes, and said substrate electrodes as second substrate electrodes other than said first substrate electrodes are provided for said electrodes of said electronic part other than in said groups of electrodes; and

solder bumps including first solder bumps connected with said groups of electrodes and said first substrate electrodes and second solder bumps connected with said second substrate electrodes and said electrodes of said electronic part other than said groups of electrodes.

8. (Previously Presented) A back electrode electronic part according to claim 7, wherein said electrodes of said electronic part are arranged in a matrix, and said groups of electrodes are corner portions.

9. (Previously Presented) A back electrode electronic part according to claim 7, wherein one of said integrated electrodes of said group is a non-contact electrode which is not connected to said circuit.

10. (Previously Presented) A back electrode electronic part according to claim 7, wherein one of said integrated electrodes of said group is a signal electrode.

11. (Previously Presented) A back electrode electronic part according to claim 7, wherein one of said electrodes of said group is a ground potential electrode.

12. (Previously Presented) A back electrode electronic part according to claim 7, wherein one of said electrodes of said group is a power supply potential electrode.

13. (Previously Presented) A back electrode electronic part according to claim 1, wherein said group of electrodes are directly connected to said first solder bump.

14. (Previously Presented) A back electrode electronic part according to claim 1, wherein said electrodes arranged for solder bumps protrude from said electronic part so as to support said solder bumps.

15. (Previously Presented) A back electrode electronic part according to claim 1, wherein said electrodes arranged for solder bumps are provided on the rearmost surface of said electronic part.

16. (Currently Amended) A back electrode electronic part according to claim 7, wherein said ~~group~~ groups of electrodes are directly connected to said first solder bump.

17. (Previously Presented) A back electrode electronic part according to claim 7, wherein said electrodes arranged for solder bumps protrude from said electronic part so as to support said solder bumps.

18. (Previously Presented) A back electrode electronic part according to claim 7, wherein said electrodes arranged for solder bumps are provided on the rearmost surface of said electronic part.

19. (Previously Presented) A back electrode electronic part comprising:
at least two first electrodes positioned on a rear surface of said electronic part so as to be connected to a first solder bump;
at least one second electrode positioned on a rear surface of said electronic so as to be connected to a second solder bump;
wherein said first solder bump has a larger lateral cross section than said second solder bump.

20. (Previously Presented) A back electrode electronic part according to claim 18, wherein each of said first electrodes and second electrode are arranged in a matrix on said rear surface of said electronic part.

21. (New) A back electrode electronic part comprising:
a main body including a circuit; and
electrodes arranged for solder bumps and supported on a back surface portion of said electronic part and connected to said circuit; wherein

said electrodes are arranged into groups of electrodes at portions of the electrode arrangement;

at least one of said groups of electrodes is connected to a first solder bump which is larger than second solder bumps connected to said electrodes arranged other than in said groups of electrodes; and

said groups of electrodes include electrodes having a substantially same potential level when said circuit operates.

22. (New) A back electrode electronic part comprising:

at least two first electrodes supported on a rear surface of said electronic part and connected to a first solder bump;

at least one second electrode supported on a rear surface of said electronic part and connected to a second solder bump;

wherein said first solder bump has a larger lateral cross section than said second solder bump.